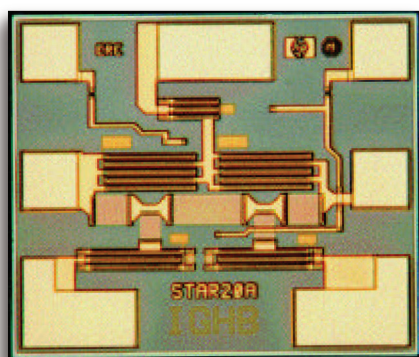


Keysight 1GG7-4082

DC-6 GHz 0/20 dB

Single Step Attenuator



Data Sheet

Features

- Frequency range:
DC to 6.0 GHz
- Attenuation values:
Single Bit
20 dB
- Min. insertion loss:
< 0.8 @ 3 GHz
< 1.4 @ 6 GHz
- Step accuracy:
 ± 0.7 @ 3 GHz
 ± 0.9 @ 6 GHz
- Return loss:
20 dB through 3 GHz
15 dB through 6 GHz
- Switching speed:
< 1 μ s (10% to 90% T_R)
- $P_{-1\text{ dB}}$:
25 dBm @ 10 MHz
30 dBm @ 3 GHz
- Distortion
SHI: + 95 dBm
THI: + 65 dBm
TOI: + 56 dBm

Description

The 1GG7-4082 is a single bit, 0/20 dB single step attenuator designed for low insertion loss and low distortion from DC to 6 GHz. It is intended for use as a general-purpose solid-state step-attenuator for RF instrumentation or commercial communication systems.

This device incorporates two 10 dB “T” attenuators combined with integral series and shunt MESFET switching elements. The 1GG7-4082 also incorporates a unique diode/resistor bias topology to improve low frequency RF performance and is fabricated with Keysight Technologies, Inc. GaAs FET MMIC process which is specifically designed to eliminate GaAs anomalies common in control circuit components.

Absolute maximum ratings¹

Symbol	Parameters/conditions	Min.	Max.	Units
$V_{C1,2}$	Control line voltages	-12	+12	Volts
$V_{RF(in/out)}$	DC input/output voltage			
$P_{in(CW)}$	CW RF input power		30	dBm
T_{op}	Operating temperature	-55	+125	°C
T_{st}	Storage temperature	-65	+165	°C
T_{max}	Max. assembly temperature		300	°C

1. Operation in excess of any one of these may result in permanent damage to this device $T_A = 25\text{ °C}$ except for T_{op} , T_{st} , and T_{max} .

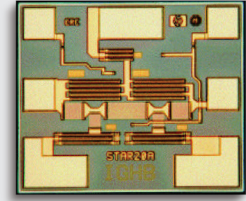
DC specifications/physical properties

($T_A = 25\text{ °C}$)

Symbol	Parameters/conditions	Min.	Typ.	Max.	Units
$V_{C1,2,3,4(+)}$	Positive control line voltage	7	10	10.5	Volts
$V_{C1,2,3,4(-)}$	Negative control line voltage	-10.5	-10	-7	Volts
$I_{L(+)}$	Positive control line leakage current ($V_{C1,2,3,4} = +10\text{ volts}$)			50	μA
$I_{L(-)}$	Negative control line leakage current ($V_{C1,2,3,4} = -10\text{ volts}$)			50	μA

Typical attenuation temperature coefficients

Symbol	Parameters/conditions	Units					
α_T	Frequency	50 MHz	1 GHz	2 GHz	3 GHz	4 GHz	
	@ Min. insertion loss state	.0008	.0008	.0008	.0007	.0006	dBc/ °C
	@ -20 dB state	-.0018	-.0018	-.0016	-.0014	-.0010	



- Chip size:
900 x 760 (35.4 x 29.9 mils)
- Chip size tolerance:
 $\pm 10\text{ }\mu\text{m}$ ($\pm 0.4\text{ mils}$)
- Chip thickness:
 $127 \pm 15\text{ }\mu\text{m}$ ($5.0 \pm 0.6\text{ mils}$)
- Small pad dimensions:
 $114 \times 114\text{ }\mu\text{m}$ ($4.5 \times 4.5\text{ mils}$)
- Large pad dimensions:
 $114 \times 228\text{ }\mu\text{m}$ ($4.5 \times 9.0\text{ mils}$)

RF specifications

($T_A = 25\text{ }^{\circ}\text{C}$, $Z_0 = 50\text{ }\Omega$, $V_{C1,2} = \pm 10\text{ volts}$)

Symbol	Parameters/conditions	Typ. ¹	Min.	Typ.	Max.	Min.	Typ.	Max.	Units
BW	Guaranteed operating bandwidth	0.01		DC to 30			DC to 6.0		GHz
$IL_{(min)}$	Minimum insertion loss ($V_{C1} = +10\text{ V}$, $V_{C2} = -10\text{ V}$)	0.5		0.7	0.8		1.3	1.4	dB
$\Delta_{acc.}$	Attenuation step (@ -20 dB state)		19.3	20	20.3	19.1	19.8	20.4	dB
RL	Return loss				20			15	dB
T_R	Rise time switching speed (10% to 90% of RF swing, $f_0 = 3\text{ GHz}$)			1			1		μs
SHI	Second harmonic intercept point (Referred to P_{in})			95			65	95	dBm
THI	Third harmonic intercept point (Referred to P_{in})			65			65		dBm
TOI	Two-tone third order lintercept point (For two-tone power levels <+20 dBm) (Referred to P_{in})			56				56	dBm
P_{-1dB}	Input power @ 1 dB increase in insertion loss	25		30			30		dBm
$P_{in}(\text{max})$	Maximum continuous RF input power				27			27	dBm

1. Typical performance <10 MHz

Applications

The 1GG7-4082 is designed for use in instrumentation, communications, radar, ECM, EW, and many other systems requiring fast switching speed, low distortion to input signals, and high cycle lifetimes. It can be used for pulse modulation, port isolation, replacement of mechanical relays, and in any application requiring the advantages of solid-state performance.

This device does not include any on-chip driver circuitry. An external driver circuit is required to convert TTL or ECL logic signals to the $\pm 10\text{ volt}$ switching levels required by this device.

Figure 3 shows the device assembly diagram for operation through 6 GHz. Dual RF input and output bonds are recommended for assemblies where the device to thin film circuit gap exceeds 10 mils.

Logic table

($V_{C1,2}$ typical values in volts)

Attenuation setting	V_{C1}	V_{C2}
Min. insertion loss	+10	-10
-20 dB state	-10	+10

Assembly Techniques

This device is compatible with Au-Sn eutectic or conductive epoxy processes. Gold thermosonic ball or wedge bonding is recommended for all bonds. The bond pads are designed to be large enough to facilitate autobonding. The top and bottom metallization is gold.

GaAs MMICs are ESD sensitive. ESD preventive measures must be employed in all aspects of storage, handling, and assembly.

MMIC ESD precautions, handling considerations, die attach and bonding methods are critical factors in successful GaAs MMIC performance and reliability.

RoHS Compliance

This device is RoHS Compliant. This means the component meets the requirements of the European Parliament and the Council of the European Union Restriction of Hazardous Substances Directive 2011/65/EU, commonly known as RoHS.

The six regulated substances are lead, mercury, cadmium, chromium VI (hexavalent), polybrominated biphenyls (PBB) and polybrominated biphenyl ethers (PBDE). RoHS compliance implies that any residual concentration of these substances is below the RoHS Directive's maximum concentration values (MVC); being less than 1000 ppm by weight for all substances except for cadmium which is less than 100 ppm by weight.

Additional References

Keysight document, *GaAs MMIC ESD, Die Attach and Bonding Guidelines - Application Note* (5991-3484EN) provides basic information on these subjects.

Simplified schematic

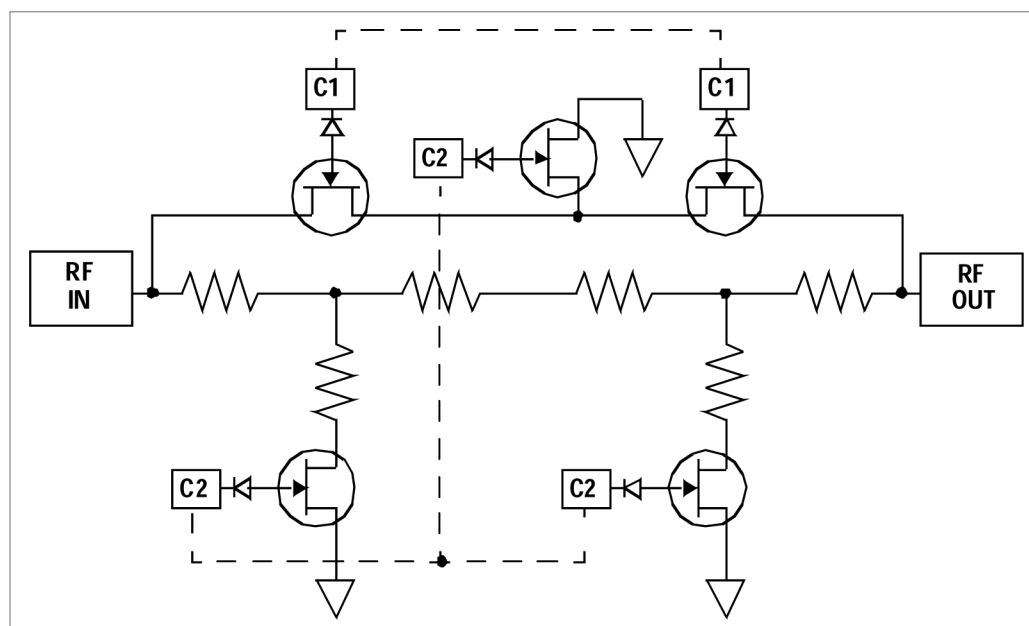


Figure 1. 1GG7-4082 simplified schematic

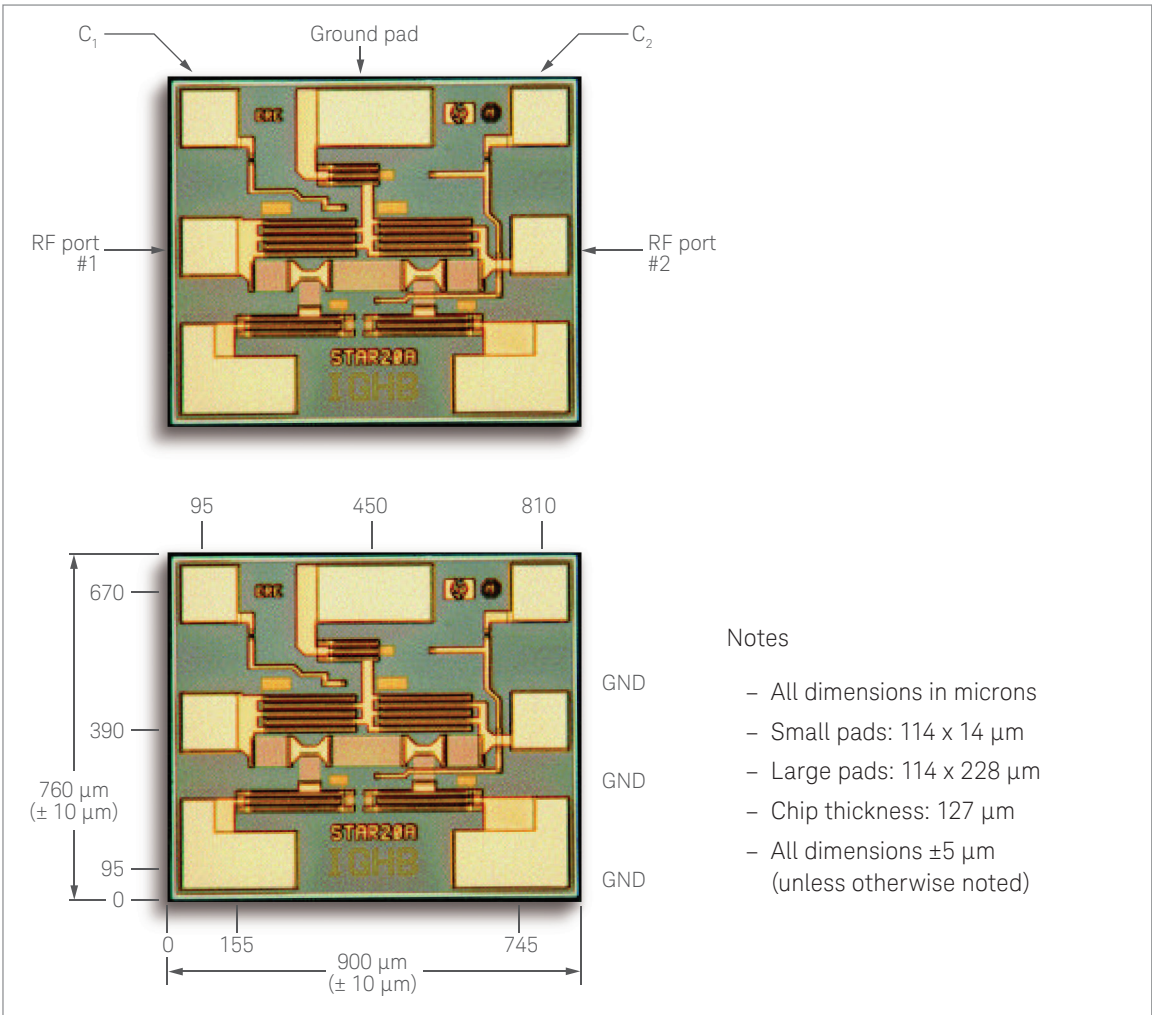


Figure 2. 1GG7-4082 bond pad locations

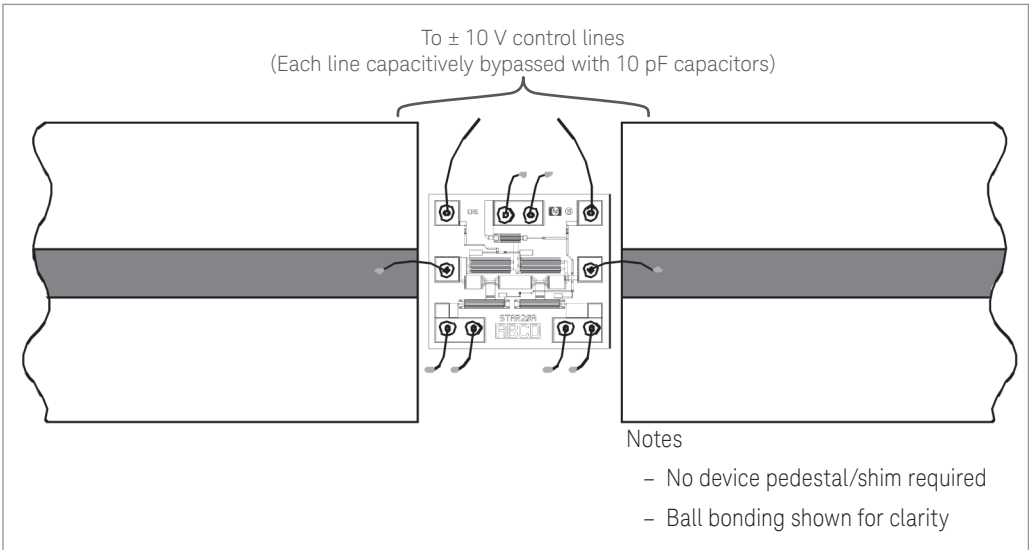


Figure 3. 1GG7-4082 assembly diagram

Supplemental Data

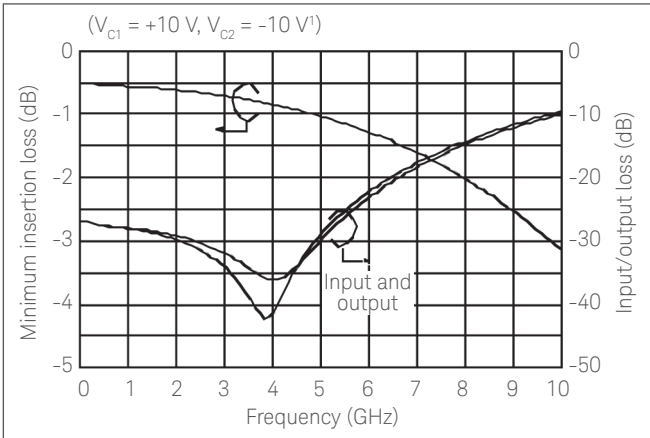


Figure 4. Minimum insertion loss and return loss vs. frequency

1. Data obtained from small-signal linear modeling

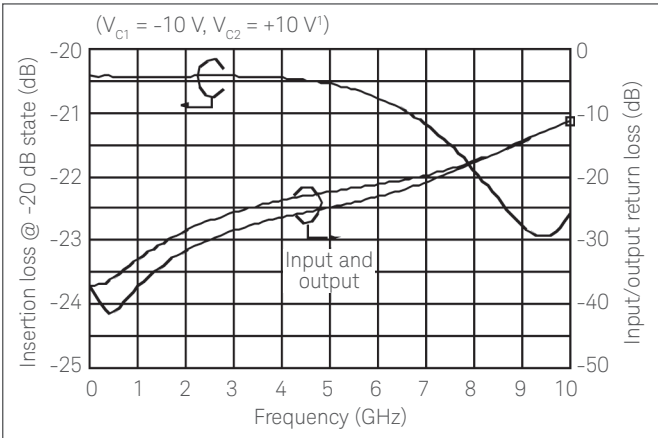


Figure 5. Insertion loss @ -20 dB state and return loss vs. frequency

1. Data obtained from small-signal linear modeling

Typical S-parameters: minimum insertion loss state¹

(T_A = +25 °C, V_{C1} = +10 V, V_{C2} = -10 V, Z_{in} = Z_{out} = 50 Ω)

Frequency (GHz)	S ₁₁			S ₁₂			S ₂₁			S ₂₂		
	dB	Mag	Ang	dB	Mag	Ang	dB	Mag	Ang	dB	Mag	Ang
0.001	-25.9	0.051	-0.05	-0.45	0.949	-0.01	-0.45	0.949	-0.01	-25.9	0.051	-0.05
0.01	-25.9	0.051	-0.61	-0.45	0.949	-0.13	-0.45	0.949	-0.13	-25.9	0.051	-0.61
0.1	-26.3	0.049	-5.1	-0.48	0.947	-1.2	-0.48	0.947	-1.2	-26.3	0.049	-5.1
0.5	-27.5	0.042	-5.4	-0.54	0.940	-5.1	-0.54	0.940	-5.1	-27.6	0.042	-5.2
1.0	-27.9	0.040	-5.2	-0.56	0.938	-10.0	-0.56	0.938	-10.0	-28.1	0.040	-4.8
1.5	-28.4	0.038	-6.9	-0.58	0.935	-14.9	-0.58	0.935	-14.9	-28.7	0.037	-6.1
2.0	-29.1	0.035	-10.2	-0.61	0.932	-19.8	-0.61	0.932	-19.8	-29.7	0.033	-8.6
2.5	-30.2	0.031	-15.7	-0.65	0.927	-24.8	-0.65	0.927	-24.8	-31.4	0.027	-12.8
3.0	-31.8	0.026	-25.0	-0.71	0.922	-29.8	-0.71	0.922	-29.8	-34.0	0.020	-20.7
3.5	-34.1	0.020	-42.5	-0.77	0.916	-34.8	-0.77	0.916	-34.8	-38.7	0.012	-41.5
4.0	-36.1	0.016	-78.1	-0.84	0.908	-39.8	-0.84	0.908	-39.8	-41.6	0.008	-115.2
4.5	-34.1	0.020	-122.9	-0.92	0.899	-44.9	-0.92	0.899	-44.9	-34.3	0.019	-161.7
5.0	-29.9	0.032	-149.5	-1.0	0.889	-50.0	-1.0	0.889	-50.0	-29.0	0.035	-175.8
5.5	-26.2	0.049	-163.9	-1.1	0.877	-55.1	-1.1	0.877	-55.1	-25.2	0.055	176.5
6.0	-23.2	0.069	-173.5	-1.3	0.864	-60.2	-1.3	0.864	-60.2	-22.3	0.077	170.6
7.0	-18.5	0.119	172.7	-1.6	0.832	-70.5	-1.6	0.832	-70.5	-17.7	0.130	160.7
8.0	-15.0	0.179	161.3	-2.0	0.794	-80.8	-2.0	0.794	-80.8	-14.4	0.191	151.3
9.0	-12.2	0.245	150.8	-2.5	0.749	-91.0	-2.5	0.749	-91.0	-11.7	0.259	142.2
10.0	-10.0	0.315	140.9	-3.1	0.698	-100.9	-3.1	0.698	-100.9	-9.6	0.330	133.2

Typical S-parameters: @ -20 dB state¹

(T_A = +25 °C, V_{C1} = -10 V, V_{C2} = +10 V, Z_{in} = Z_{out} = 50 Ω)

Frequency (GHz)	S ₁₁			S ₁₂			S ₂₁			S ₂₂		
	dB	Mag	Ang	dB	Mag	Ang	dB	Mag	Ang	dB	Mag	Ang
0.001	-37.2	0.014	-0.05	-20.4	0.096	-0.008	-20.4	0.096	-0.008	-37.0	0.014	0.10
0.01	-37.2	0.014	-0.75	-20.4	0.096	-0.08	-20.4	0.096	-0.08	-37.0	0.014	0.71
0.1	-37.9	0.013	-6.3	-20.4	0.096	-0.76	-20.4	0.096	-0.76	-37.0	0.014	6.4
0.5	-41.2	0.008	28.2	-20.4	0.095	-3.1	-20.4	0.095	-3.1	-35.8	0.016	32.6
1.0	-37.2	0.014	60.8	-20.4	0.095	-6.1	-20.4	0.095	-6.1	-33.0	0.022	51.9
1.5	-33.9	0.020	71.8	-20.4	0.095	-9.1	-20.4	0.095	-9.1	-30.5	0.030	61.8
2.0	-31.6	0.026	77.3	-20.4	0.095	-12.3	-20.4	0.095	-12.3	-28.5	0.037	67.5
2.5	-29.9	0.032	81.1	-20.4	0.095	-15.6	-20.4	0.095	-15.6	-26.9	0.045	71.3
3.0	-28.5	0.038	84.2	-20.4	0.095	-19.2	-20.4	0.095	-19.2	-25.7	0.052	74.1
3.5	-27.3	0.043	87.3	-20.4	0.095	-22.9	-20.4	0.095	-22.9	-24.6	0.059	76.5
4.0	-26.4	0.048	90.6	-20.5	0.095	-27.0	-20.5	0.095	-27.0	-23.7	0.065	78.8
4.5	-25.6	0.053	94.4	-20.5	0.095	-31.5	-20.5	0.095	-31.5	-23.0	0.071	81.3
5.0	-24.8	0.057	98.8	-20.5	0.094	-36.4	-20.5	0.094	-36.4	-22.4	0.076	84.2
5.5	-24.0	0.063	103.9	-20.6	0.093	-41.9	-20.6	0.093	-41.9	-21.8	0.081	87.8
6.0	-23.2	0.069	109.7	-20.8	0.092	-48.1	-20.8	0.092	-48.1	-21.2	0.087	92.0
7.0	-20.9	0.090	121.8	-21.2	0.087	-63.7	-21.2	0.087	-63.7	-19.8	0.102	102.8
8.0	-17.9	0.127	130.9	-21.9	0.080	-85.8	-21.9	0.080	-85.8	-17.6	0.131	114.2
9.0	-14.5	0.188	133.7	-22.8	0.073	-119.5	-22.8	0.073	-119.5	-14.6	0.186	121.0
10.0	-11.3	0.271	129.6	-22.6	0.074	-168.5	-22.6	0.074	-168.5	-11.4	0.268	120.3

1. Data obtained from small-signal linear modeling

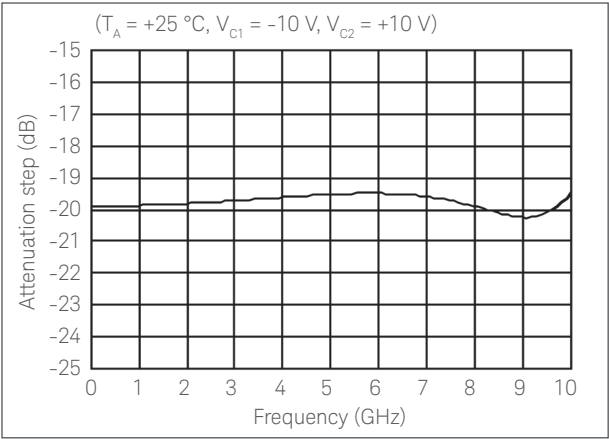


Figure 6. Attenuation step values vs. frequency

Typical attenuation step values¹

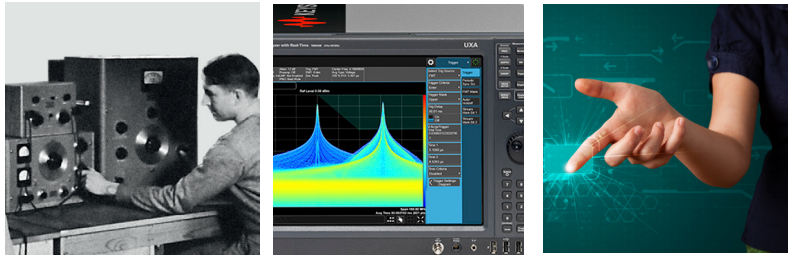
(T_A = +25 °C, V_{C1} = -10 v, V_{C2} = +10 v, Z_{in} = Z_{out} = 50 Ω)

Frequency (GHz)	-20 dB state (dB)
0.001	-19.9
0.01	-19.9
0.1	-19.9
0.5	-19.9
1.0	-19.9
1.5	-19.8
2.0	-19.8
2.5	-19.8
3.0	-19.7
3.5	-19.7
4.0	-19.6
4.5	-19.6
5.0	-19.5
5.5	-19.5
6.0	-19.5
6.5	-19.5
7.0	-19.6
7.5	-19.7
8.0	-19.9
8.5	-20.1
9.0	-20.2
9.5	-20.1
10.0	-19.4

1. Data obtained from small-signal linear modeling

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The product described in this data sheet is RoHS Compliant. See RoHS Compliance section for more details.

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